	· · · · · · · · · · · · · · · · · · ·		DB	Time stamp
L Number	Hits	Search Text		2003/05/11 17:17
2	53446	substrate near5 bond\$3	USPAT;	2003/03/11 1/:1/
			US-PGPUB	
3	38607	(substrate near5 bond\$3) and (remov\$3	USPAT;	2003/05/11 17:13
		detach\$3)	US-PGPUB	1
4	2959	((substrate near5 bond\$3) and (remov\$3	USPAT;	2003/05/11 17:17
] 3	2,33	detach\$3)) and (metal near5 wir\$3)	US-PGPUB]
5	2279	(((substrate near5 bond\$3) and (remov\$3	USPAT;	2003/05/11 17:17
3	2219	detach\$3)) and (metal near5 wir\$3)) and	US-PGPUB	
			05 10105	
		(insulat\$3 dielectric)	HCDAM.	2003/05/11 14:54
6	115	(remov\$3 separat\$3 detach\$3) near10 (metal	USPAT;	2003/03/11 14.54
		near5 wire) near10 (base substrate)	US-PGPUB	0000/05/11 14 55
7	168	(remov\$3 separat\$3 detach\$3) near10 (metal	EPO; JPO;	2003/05/11 14:55
		near5 wire) near10 (base substrate)	DERWENT;	
			IBM_TDB	
8	33518	substrate near5 bond\$3	EPO; JPO;	2003/05/11 17:13
			DERWENT;	
			IBM TDB	
9	3974	(substrate near5 bond\$3) and (remov\$3	EPO; JPO;	2003/05/11 17:13
1		detach\$3)	DERWENT;	
		400401140)	IBM TDB	
10	924	((substrate near5 bond\$3) and (remov\$3	EPO; JPO;	2003/05/11 17:13
10	724	detach\$3)) and (insulat\$3 dielectric)	DERWENT;	2000, 00, 22 21120
		detachips), and (insuracys dielectric)	IBM TDB	1
, ,	24	(((substrate near5 bond\$3) and (remov\$3	EPO; JPO;	2003/05/11 17:14
11	24	detach\$3)) and (insulat\$3 dielectric))	DERWENT;	2003/03/11 17:14
		and (metal near5 wir\$3)	IBM_TDB	0000 (05 (11 17 04
12	22356	connection near5 substrate	USPAT;	2003/05/11 17:24
			US-PGPUB	
13	2372	1 1	USPAT;	2003/05/11 17:24
		near5 wir\$3)	US-PGPUB	
14	2087	((connection near5 substrate) and (metal	USPAT;	2003/05/11 17:18
		near5 wir\$3)) and (insulat\$3 dielectric)	US-PGPUB	
15	1186		USPAT;	2003/05/11 17:24
		near5 wir\$3)) and (insulat\$3 dielectric))	US-PGPUB	
		and glass		
16	13250	connection near5 substrate	EPO; JPO;	2003/05/11 17:24
	15250	Connection nears substrace	DERWENT;	2000,00,11 1:121
			IBM TDB	
17	276	(connection near5 substrate) and (metal	EPO; JPO;	2003/05/11 17:24
1 /	2/6		DERWENT;	2003/03/11 17.24
		near5 wir\$3)		
			IBM_TDB	0000/05/11 17 04
18	19	((connection near5 substrate) and (metal	EPO; JPO;	2003/05/11 17:24
		near5 wir\$3)) and glass	DERWENT;	
			IBM TDB	